

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE SPECIFICATION:**

Paragraph beginning at line 8 of page 4 has been amended as follows:

--FIGURE 2 is [the] a top view of a structure of [the first embodiment] a leadframe package according to an embodiment of the present invention.--

Paragraph beginning at line 10 of page 4 has been amended as follows:

--FIGURE 3 is the top view of a structure of [the first embodiment] a leadframe package according to another embodiment of the present invention.--

Paragraph beginning at line 14 of page 4 has been amended as follows:

--The present invention discloses a novel structure of a package 100. FIGURE 1 is a cross sectionalal view of [an embodiment] the structure of the package 100 of the present invention. FIGURE 2 and FIGURE 3 are [the] respective top views of two different embodiments of the present invention.--

Paragraph beginning at line 5 page 6 has been amended as follows:

--Still turning to FIGURE 2, a tap 28 is used to fix the inner leads 12. Another embodiment is illustrated in FIGURE 3, the example

includes the dummy chip 18 fixed by a few inner leads 12a [adheive] adhesive tapes 18. Alternate distribution of the inner leads 12a and 12b can improve the yield, especially high-density wire bonding. Further inner leads 12b are set outside the dummy chip 18, the die is connected to the inner leads 12b by means of bonding wires 24.--

Paragraph beginning at line 20 page 4 has been amended as follows:

--As shown therein, the package 10 includes a lead frame 100 without conventional die paddle to receive the die. The lead frame 10 has inner leads 12 and outer leads 14. In the present invention, molding material (compound) 16 encapsulates a die 20 and a dummy chip 18 configured as a stacked structure. The dummy chip 18 is arranged on a lower portion of a molding compound 16 and a lower surface of the dummy chip 18 may be exposed. The dummy chip refers to a substrate without IC formed therein. Preferably, the material for the dummy chip 18 includes but is not limited to silicon. The dummy chip 18 may be fixed by the tapes 28 adhesive on the inner leads 12 of the lead frame 10. The dummy chip 18 includes one or more pads 22 configured around the surface of the dummy chip 18 to connect the inner leads 12. The die 20 is stacked on the upper surface of the dummy chip 18 by using adhesive material 26. The benefit of the present invention is that the metal sink is omitted, which may reduce manufacturing costs. Further, die paddle is not necessary for the